

HVD133A

Silicon Epitaxial Planar Pin Diode for Antenna Switching

REJ03G0171-0100Z Rev.1.00 Jan.21.2004

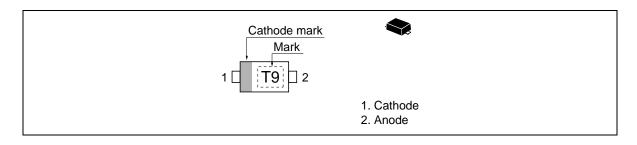
Features

- An optimal solution for antenna switching in mobile phones.
- Low capacitance. (C1 = 1.0 pF max)
- Low forward resistance. (rf = $0.7 \Omega \text{ max}$)
- Super small Flat Package (SFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HVD133A	Т9	SFP

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Reverse voltage	V_R	30	V
Power dissipation	Pd	150	mW
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

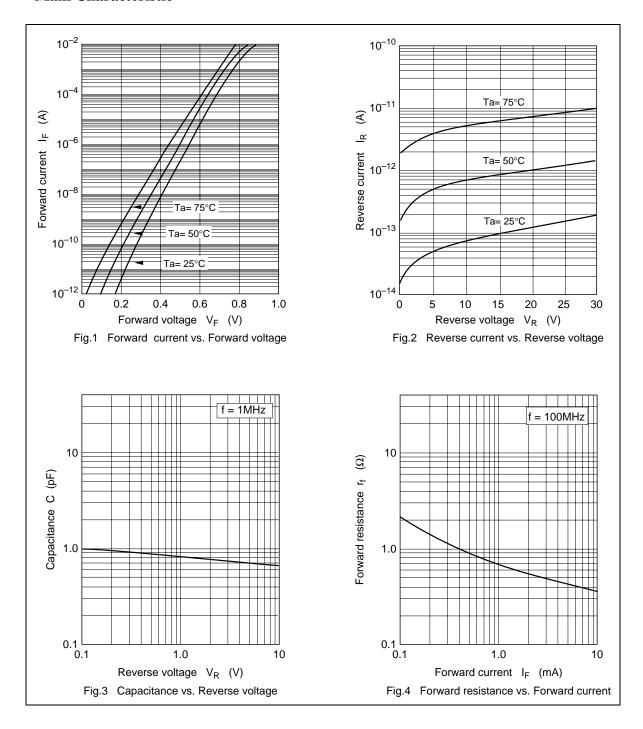
Electrical Characteristics

 $(Ta = 25^{\circ}C)$

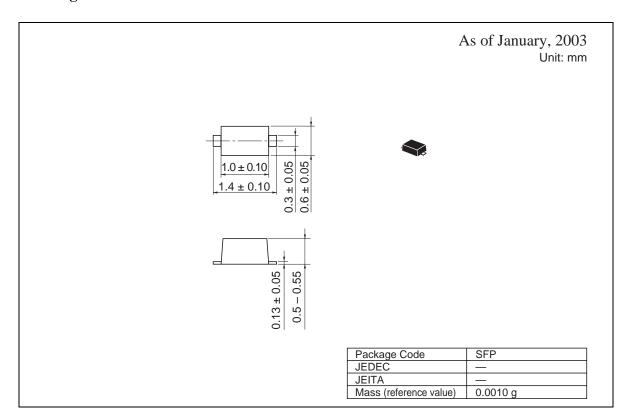
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse voltage	V_R	30	_	_	V	$I_R = 1 \mu A$
Reverse current	I _R	_	_	100	nA	V _R = 25 V
Forward voltage	V _F	_	_	0.85	V	I _F = 2 mA
Capacitance	C ₁	_	_	1.00	рF	V _R = 1 V, f = 1 MHz
	C ₆	_	_	0.90	<u> </u>	V _R = 6 V, f = 1 MHz
Forward resistance	r _f	_	0.55	0.70	Ω	I _F = 2 mA, f = 100 MHz

Note: Please do not use the soldering iron due to avoid high stress to the SFP package.

Main Characteristic



Package Dimensions



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